



## CST3020 N-Ch and P-Ch Fast Switching MOSFETs

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

## CST3020 Product Summary

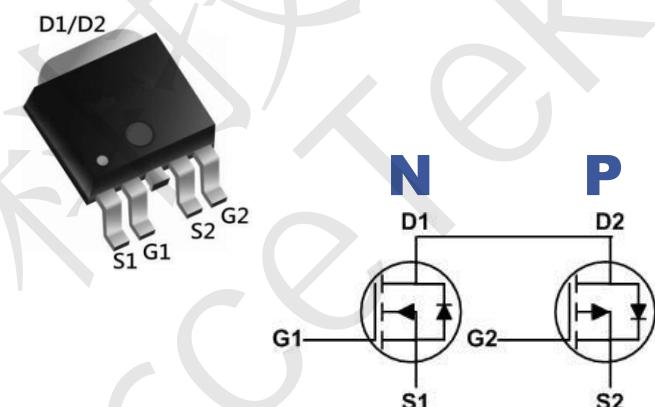


BVDSS	RDS(on)	ID
30V	15 mΩ	20A
-30V	25 mΩ	-23A

## CST3020 Description

The CST3020 is the high performance complementary N-ch and P-ch MOSFETs with high cell density, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications. The CST3020 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

## CST3020 TO252-4 Pin Configuration



## CST3020 Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
V <sub>DS</sub>	Drain-Source Voltage	30	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	±20	V
I <sub>D</sub> @T <sub>c</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	20	-23	A
I <sub>D</sub> @T <sub>c</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	15	-14	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	60	-60	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	26.6	38	mJ
P <sub>D</sub> @T <sub>c</sub> =25°C	Total Power Dissipation <sup>4</sup>	20.8	20.8	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	2	2	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	6	°C/W



## CST3020 N-Ch and P-Ch Fast Switching MOSFETs

CST3020 N-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $\text{I}_D=1\text{mA}$	---	0.023	---	$\text{V}/^\circ\text{C}$
$\text{R}_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_D=10\text{A}$	---	15	20	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_D=6\text{A}$	---	20	25	
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_D=250\mu\text{A}$	1.0	---	2.5	V
$\Delta \text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-4.2	---	$\text{mV}/^\circ\text{C}$
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=24\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$\text{V}_{\text{DS}}=24\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$\text{g}_{\text{fs}}$	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}$ , $\text{I}_D=10\text{A}$	---	14	---	S
$\text{R}_g$	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2.3	---	$\Omega$
$\text{Q}_g$	Total Gate Charge (4.5V)	$\text{V}_{\text{DS}}=20\text{V}$ , $\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_D=10\text{A}$	---	5	---	$\text{nC}$
$\text{Q}_{\text{gs}}$	Gate-Source Charge		---	1.11	---	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		---	2.61	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=12\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{R}_g=3.3\Omega$	---	7.7	---	$\text{ns}$
$\text{T}_r$	Rise Time		---	46	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	11	---	
$\text{T}_f$	Fall Time		---	3.6	---	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=15\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	416	---	$\text{pF}$
$\text{C}_{\text{oss}}$	Output Capacitance		---	62	---	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	51	---	

## CST3020 Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{I}_s$	Continuous Source Current <sup>1,5</sup>	$\text{V}_G=\text{V}_D=0\text{V}$ , Force Current	---	---	20	A
$\text{I}_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	40	A
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $\text{V}_{\text{DD}}=25\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $L=0.1\text{mH}$ , $\text{I}_{\text{AS}}=12.7\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $\text{I}_D$  and  $\text{I}_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



## CST3020 N-Ch and P-Ch Fast Switching MOSFETs

CST3020 P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.021	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_D=-8\text{A}$	---	25	30	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-6\text{A}$	---	30	35	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-1.0	---	-2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-4.2	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$ , $I_D=-8\text{A}$	---	12.6	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	15	---	$\Omega$
$Q_g$	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-20\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $I_D=-6\text{A}$	---	9.8	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	2.2	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	3.4	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=-24\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=3.3\Omega$ , $I_D=-1\text{A}$	---	16.4	---	$\text{ns}$
$T_r$	Rise Time		---	20.2	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	55	---	
$T_f$	Fall Time		---	10	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	930	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	148	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	115	---	

## CST3020 Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-23	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	-35	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=-25\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $L=0.1\text{mH}$ , $I_{\text{AS}}=-30\text{A}$
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



## CST3020 N-Ch and P-Ch Fast Switching MOSFETs

## CST3020 N-Channel Typical Characteristics

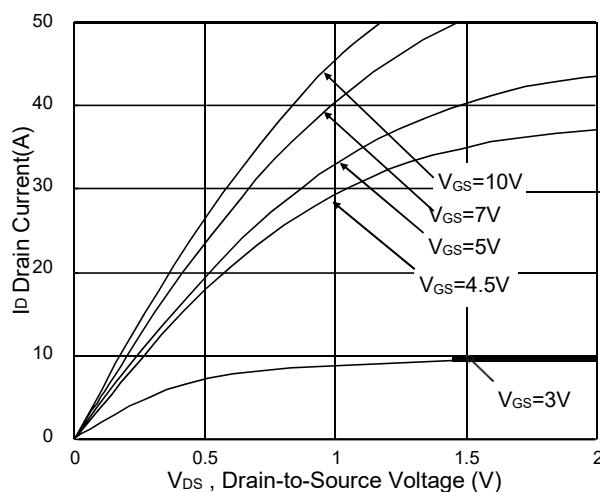


Fig.1 Typical Output Characteristics

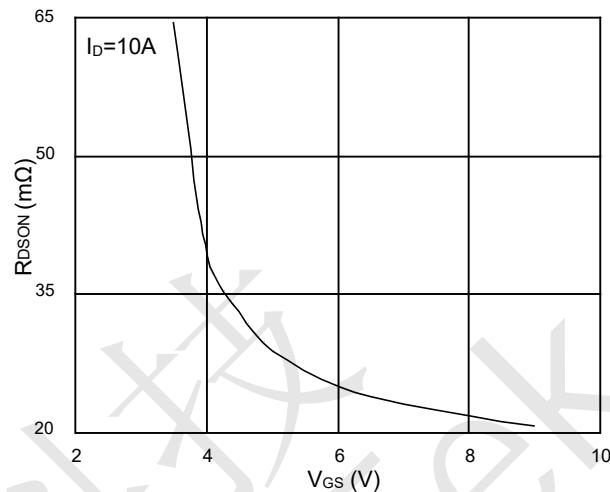


Fig.2 On-Resistance vs. Gate-Source

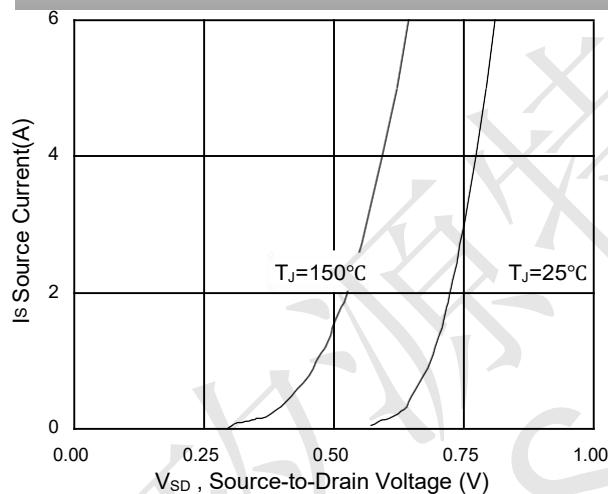


Fig.3 Forward Characteristics Of Reverse

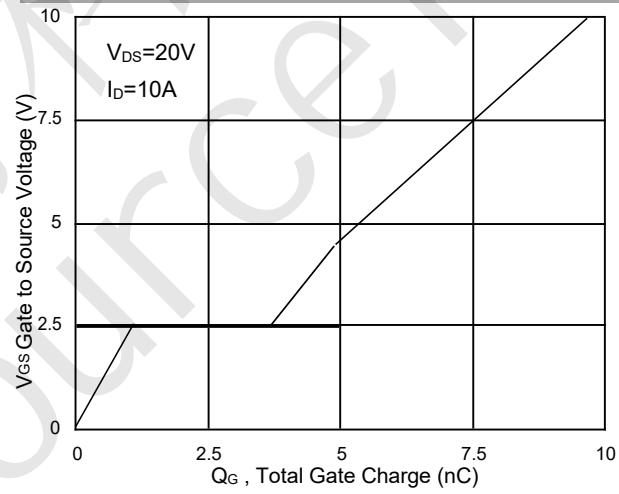
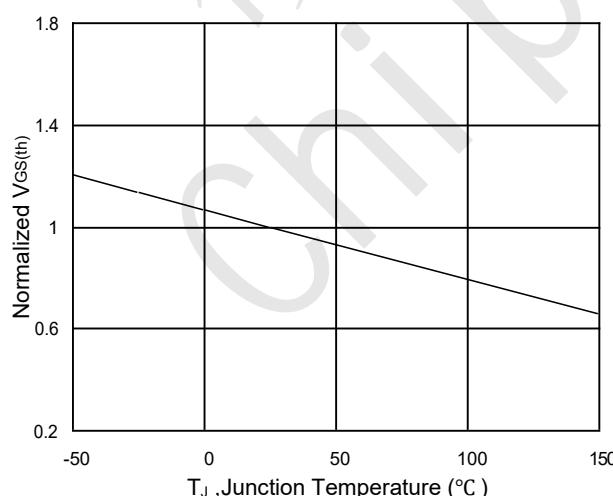
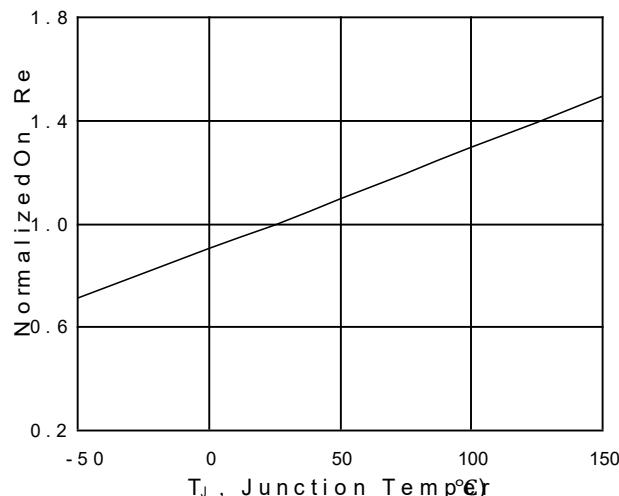


Fig.4 Gate-Charge Characteristics

Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$



CST3020 N-Ch and P-Ch Fast Switching MOSFETs

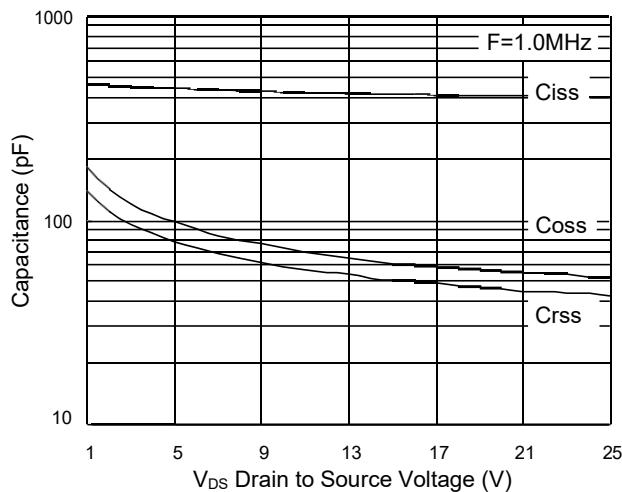


Fig.7 Capacitance

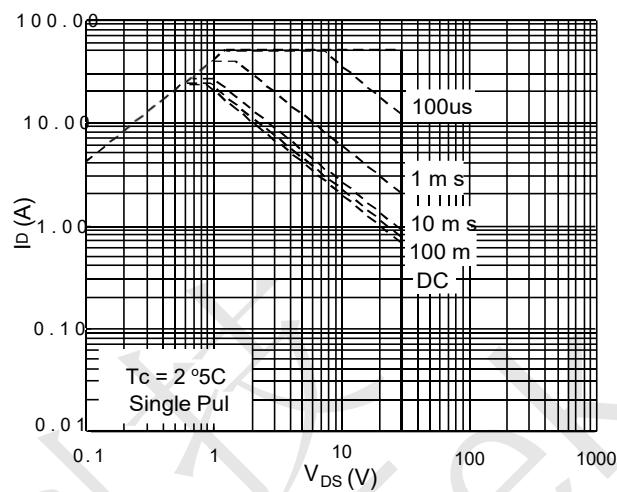
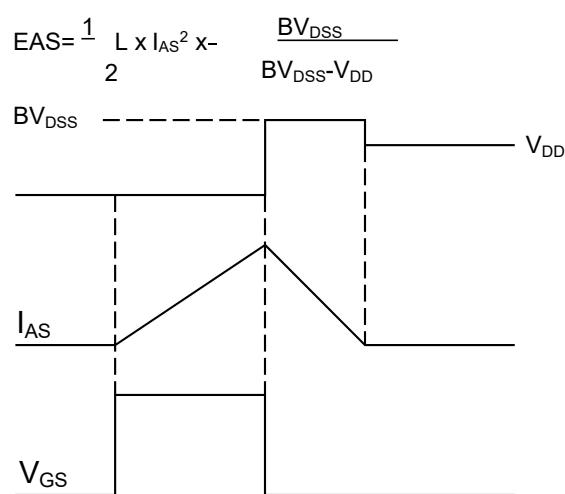
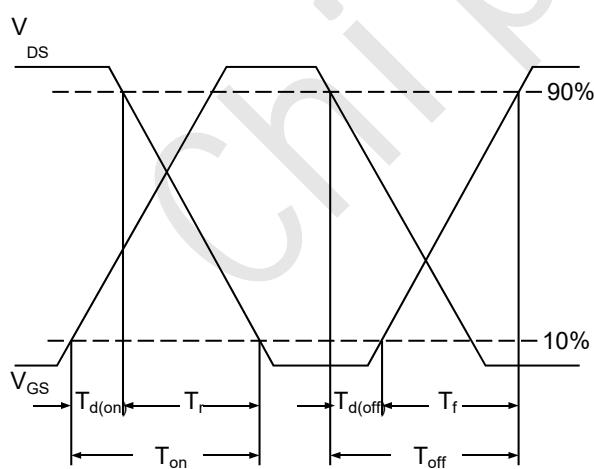


Fig.8 Safe Operating Area



Fig.9 Normalized Maximum Transient Thermal Impedance





## CST3020 N-Ch and P-Ch Fast Switching MOSFETs

## CST3020 P-Channel Typical Characteristics

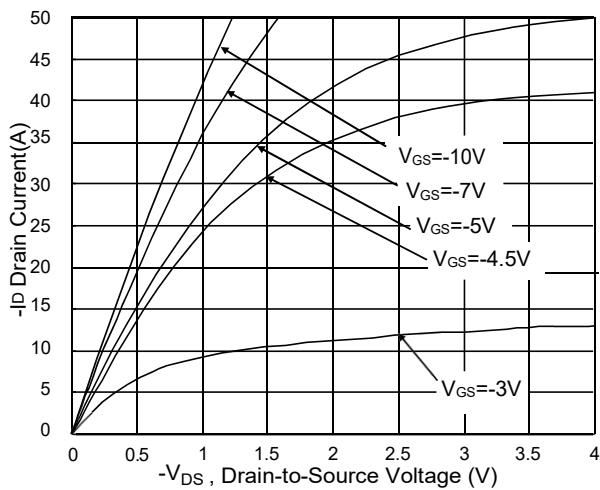


Fig.1 Typical Output Characteristics

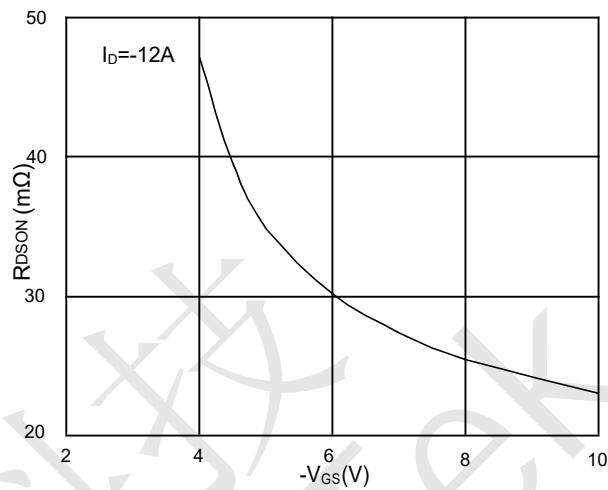


Fig.2 On-Resistance v.s Gate-Source

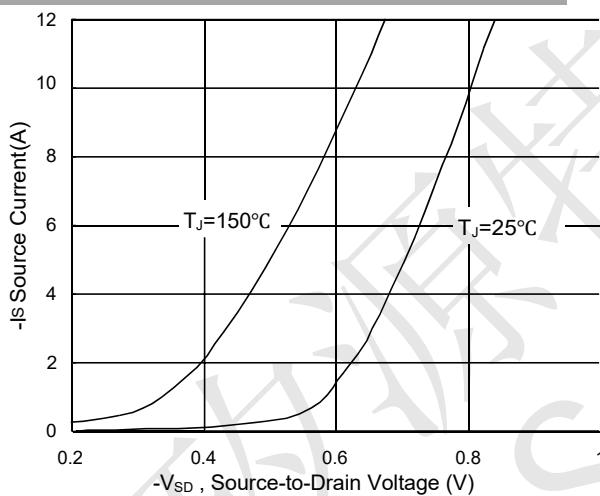


Fig.3 Forward Characteristics Of Reverse

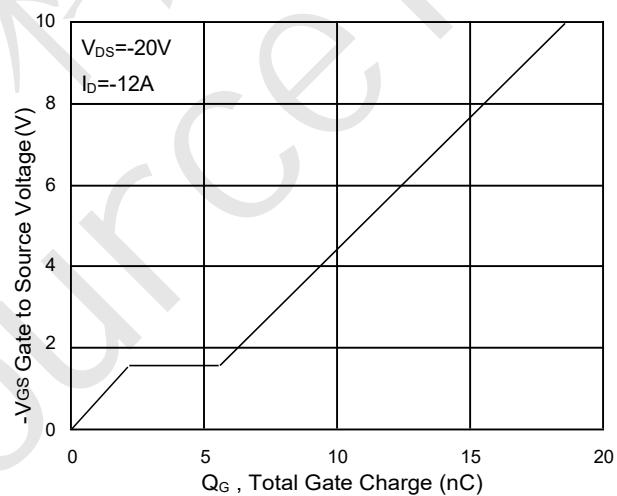


Fig.4 Gate-Charge Characteristics

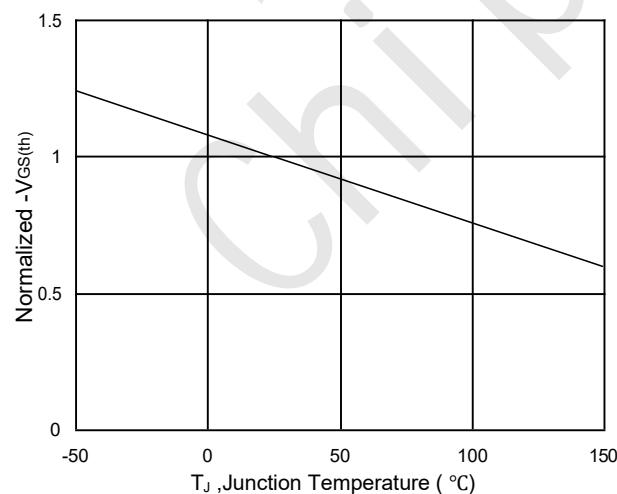


Fig.5 Normalized VGS(th) v.s TJ

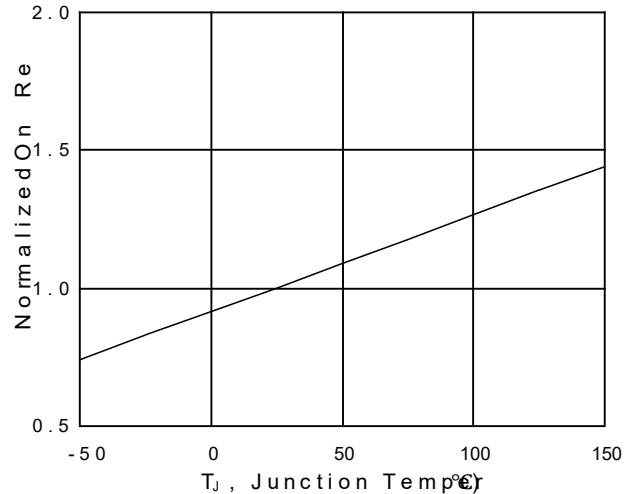


Fig.6 Normalized RDSON v.s TJ



深圳市矽源特科技有限公司

ShenZhen ChipSourceTek Technology Co. , Ltd.

### CST3020 N-Ch and P-Ch Fast Switching MOSFETs

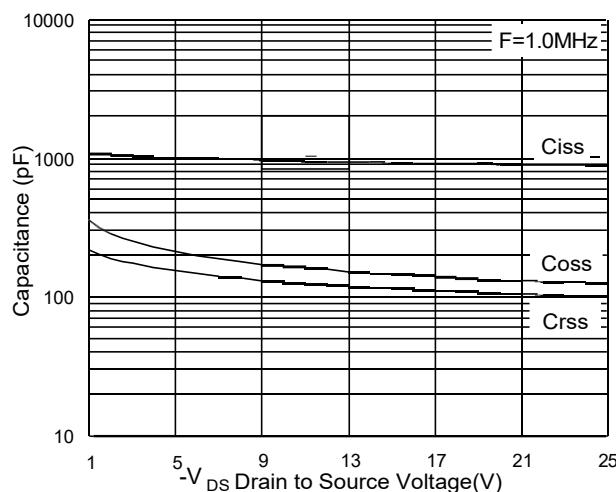


Fig.7 Capacitance

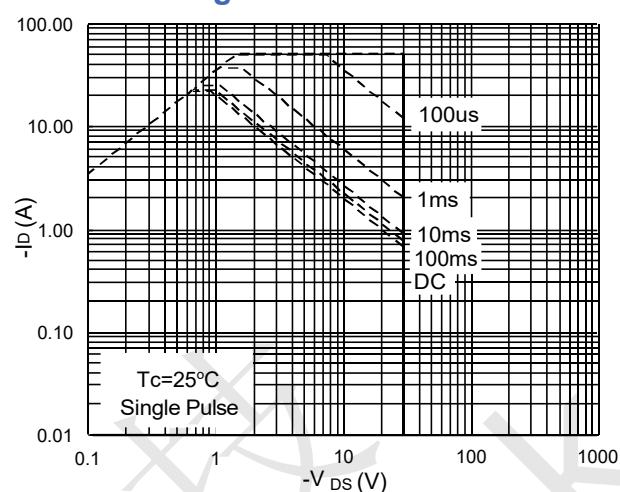


Fig.8 Safe Operating Area

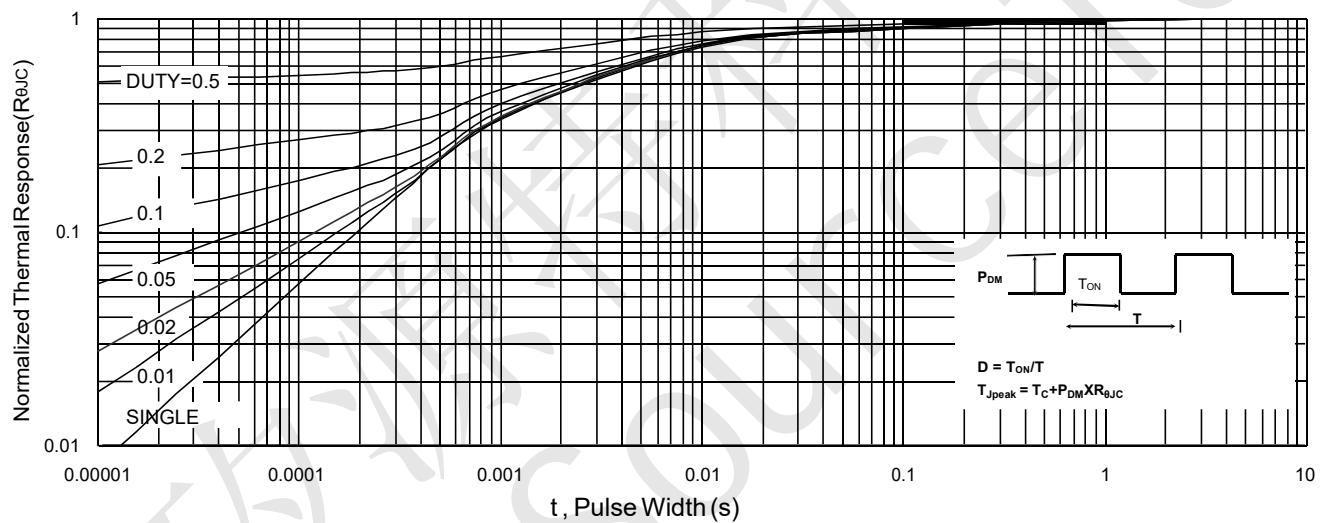


Fig.9 Normalized Maximum Transient Thermal Impedance

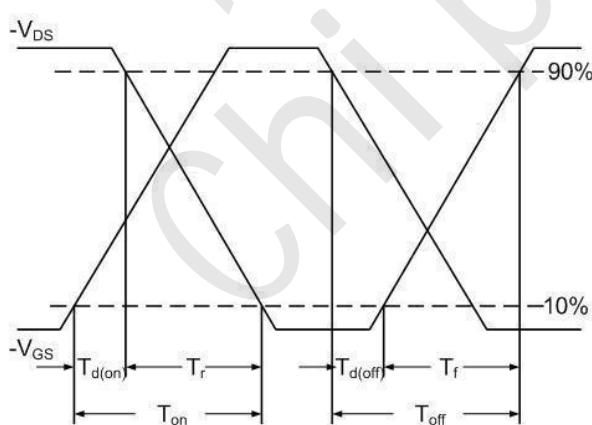


Fig.10 Switching Time Waveform

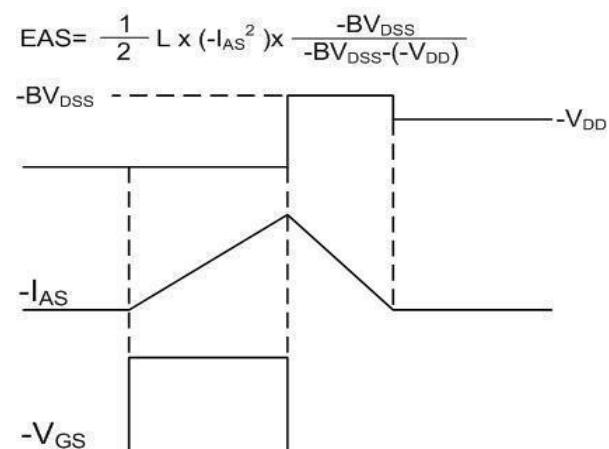


Fig.11 Unclamped Inductive Switching Waveform

